

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:) Oroup Art Unit: 2825
Benham Malekkhosravi, et al.) Examiner: To be assigned
Serial No. 10/789,066)
Filed: February 27, 2004))
For: METHOD AND ARCHITECTURE FOR INTEGRATED CIRCUIT DESIGN AND MANUFACTURE)))

PRELIMINARY AMENDMENT UNDER 37 C.F.R. §1.115

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Applicant respectfully requests entry of the following amendments to the above-captioned application before examination of this case:

Amendment to the Claims

In the Claims:

- 1. (recited) A system for integrated circuit (IC) design comprising:
- at least one structural multi-project wafer (SMPW) comprising a plurality of premanufactured and pre-validated functional blocks; and
- a streamlined IC design flow incorporating the SMPW and having no IP integration or floor planning requirements.

C	ERTIFICATE OF MAILING
	(37 C.F.R. §1.8)
	as being attached or enclosed) is being deposited with the United States Postal Service Class Mail' in an envelope addressed to the Commissioner for Patents, P.O. Box 1450,
	Karen M. Cruz
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September 2 2004	Kml
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